L Number	Hits	Search Text	DB	Time stamp
1.	22783	((conducitve adj paste) or paste or (paste adj material))	USPAT;	2003/12/14 18:14
		same advan\$4	EPO; JPO;	
			DERWENT;	
		·	USOCR	
2	2103	(((conducitve adj paste) or paste or (paste adj material))	USPAT;	2003/12/14 17:56
		same advan\$4) and (carrier or (carrier adj board))	EPO; JPO;	
		, , , , , , , , , , , , , , , , , , , ,	DERWENT;	
			USOCR	
3	1227	((((conducitve adj paste) or paste or (paste adj material))	USPAT;	2003/12/14 17:56
		same advan\$4) and (carrier or (carrier adj board))) and	EPO; JPO;	2000/12/14 11.00
		(component or die or chip or IC)	DERWENT:	
		(components and or omp or ro)	USOCR	
5	131	(((((conducitve adj paste) or paste or (paste adj	USPAT;	2003/12/14 17:57
		material)) same advan\$4) and (carrier or (carrier adj	EPO; JPO;	2003/12/14 17.57
		board))) and (component or die or chip or IC)) and (PCB		
			DERWENT;	
	440	or (circuit adj board))	USOCR	
	119	((((((conducitve adj paste) or paste or (paste adj	USPAT;	2003/12/14 18:14
		material)) same advan\$4) and (carrier or (carrier adj	EPO; JPO;	
		board))) and (component or die or chip or IC)) and (PCB	DERWENT;	
		or (circuit adj board))) and (solder or (solder adj ball) or	USOCR	
		(solder adj bump))		-
6	41	((((((conducitve adj paste) or paste or (paste adj	USPAT;	2003/12/14 18:15
		material)) same advan\$4) and (carrier or (carrier adj	EPO; JPO;	
		board))) and (component or die or chip or IC)) and (PCB	DERWENT;	
		or (circuit adj board))) and (solder or (solder adj ball) or	USOCR	
		(solder adj bump))) and (melting adj point)		
7	1346	174/250-268.ccls. and ((conducitve adj paste) or paste	USPAT;	2003/12/14 18:14
		or (paste adj material))	EPO; JPO;	2000/12/17 10:14
		(Factorial)	DERWENT;	
			USOCR	
8	930	(174/250-268.ccls. and ((conducitve adj paste) or paste	USPAT;	2003/12/14 18:14
	300	or (paste adj material))) and (solder or (solder adj ball)		2003/12/14 16:14
		or (solder adj bump))	EPO; JPO;	
		or (solder adj bullip))	DERWENT;	
9	244	(/474/250 260 colo and (/acadyoity) adi acata) as acata	USOCR	00001101111000
	244	((174/250-268.ccls. and ((conducitve adj paste) or paste	USPAT;	2003/12/14 18:33
		or (paste adj material))) and (solder or (solder adj ball)	EPO; JPO;	
		or (solder adj bump))) and (melting adj point)	DERWENT;	
			USOCR	
10	230	paste same (high\$3 adj melting adj point) same solder	USPAT;	2003/12/14 18:35
			EPO; JPO;	4
			DERWENT;	
			USOCR	
11	26	361/\$.ccls. and (paste same (high\$3 adj melting adj	USPAT;	2003/12/14 18:39
		point) same solder)	EPO; JPO;	
			DERWENT;	
			USOCR	
12	0	174/250-268/\$.ccls. and (paste same (high\$3 adj melting	USPAT;	2003/12/14 18:40
	J	adj point) same solder)	EPO; JPO;	2000/12/14 10:40
		and bound on an in	DERWENT;	
			USOCR	
13	0	257/600-800/\$ cole and (noote came (hinted adi malking		2002/40/4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4
	U	parties the first and (parties canno (mg//yo day morang	USPAT;	2003/12/14 18:40
1		adj point) same solder)	EPO; JPO;	
			DERWENT;	
45	•	474/050 0001 14	USOCR	
15	21	174/250-268.ccls. and (paste same (high\$3 adj melting	USPAT;	2003/12/14 18:42
		adj point) same solder)	EPO; JPO;	
			DERWENT;	
			USOCR	
		257/600-780.ccls. and (paste same (high\$3 adj melting	USPAT;	2003/12/14 18:42
14	45	Leviere recieció: ana (paste same (mgnyo daj menna	USFAI.	1 2000/12/14 10:42
14	45	adj point) same solder)		2003/12/14 16.42
14	45		EPO; JPO; DERWENT;	2003/12/14 10.42